



## Product Change Notification - LIAL-06FXHO065

**Date:**

21 Mar 2018

**Product Category:**

16-Bit - Microcontrollers and Digital Signal Controllers

**Affected CPNs:****Notification subject:**

CCB 3250 Initial Notice: Qualification of CuPdAu wire and G631HQ mold compound in selected products of the 160K wafer technology available in 64L TQFP package at ANAP assembly site.

**Notification text:****PCN Status:**

Initial notification **PCN**

**Type:** Manufacturing

Change

**Microchip Parts Affected:**

Please open one of the icons found on the Affected CPNs section above.

**NOTE:** For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire and G631HQ mold compound in selected products of the 160K wafer technology available in 64L TQFP package at ANAP assembly site.

**Pre Change:**

Using gold (Au) bond wire and G700L mold compound material

**Post Change:**

Using palladium coated copper with gold flash (CuPdAu) bond wire and G631HQ mold compound material

**Pre and Post Change Summary:**

	<b>Pre Change</b>	<b>Post Change</b>
<b>Assembly Site</b>	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Amkor Technology Philippine (P1/P2), INC. (ANAP)
<b>Wire material</b>	Au	CuPdAu
<b>Die attach material</b>	3230	3230
<b>Molding compound material</b>	G700L	G631HQ
<b>Lead frame material</b>	C194	C194

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire G631HQ mold compound

**Change Implementation Status:**



In Progress

**Estimated Qualification Completion Date:**

July 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

	February 2018				-->	July 2018			
Workweek	05	06	07	08		27	28	29	30
Initial PCN Issue Date			X						
Qual Report Availability						X			
Final PCN Issue Date						X			

**Method to Identify Change:**

Traceability code

**Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan.

**Revision History:**

**February 12, 2018:** Issued initial notification.

**March 21, 2018:** Revised this initial notification to be issued to all affected customers.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_LIAL-06FXHO065\\_QUAL PLAN.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

**Terms and Conditions:**

If you wish to change your product/process change notification (PCN) profile please log on to our website at [microchip.com/PCN](http://microchip.com/PCN) sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to [microchip DIRECT](#) and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

Affected Catalog Part Numbers (CPN)

DSPIC30F6011-20E/PF

DSPIC30F6011-20I/PF

DSPIC30F6011-30I/PF

DSPIC30F6012-20I/PF

DSPIC30F6012-30I/PF